



## News Release

**Kuala Lumpur 17 January 2019** Unisem (M) Berhad ("**Unisem**" or "**the Company**") wishes to announce that the Voluntary Take-over Offer undertaken by Huatian Electronics Group (HK) Limited, Huatian Technology (Malaysia) Sdn Bhd ("**HT Malaysia**"), Mr John Chia Sin Tet, Mr Alexander Chia Jhet-Wern, Jayvest Holdings Sdn Bhd and SCQ Industries Sdn Bhd (collectively "**Joint Offerors**") has been successfully completed.

The total valid acceptances received by HT Malaysia was 428,553,254 Offer Shares, representing approximately 58.94% of the issued share capital of Unisem (excluding treasury shares). Mr John Chia (together with Mr Alexander Chia Jhet-Wern, Jayvest Holdings Sdn Bhd and SCQ Industries Sdn Bhd (collectively "**Malaysian Offerors**")) currently holds approximately 24.28% of shareholding interest in Unisem.

The level of acceptances received by the Joint Offerors under the Offer had resulted in the public shareholding spread of Unisem being less than the required 25% of the issued share capital of Unisem (excluding treasury shares). Consequently the Joint Offerors will procure Tianshui Huatian Technology Co., Ltd. ("**TSHT**") (via HT Malaysia) to comply with the undertaking in the collaboration agreement dated 12 September 2018 between TSHT, Mr John Chia and the Malaysian Offerors whereby TSHT (via HT Malaysia) will sell its Unisem shares to the extent required to meet the Public Spread Requirement within three (3) months from the closing date of the Offer if allowed by Bursa Securities or such extended timeframe as may be allowed by Bursa Securities to enable Unisem to comply with the Public Spread Requirement.

Mr John Chia, Chairman and Group Managing Director of Unisem, said, "We are pleased that this important transaction has been successfully completed. We will continue to deliver further value to our customers, enhance shareholder value and achieving the synergies that we expect from this collaboration with TSHT."

### **About Unisem**

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. The Company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China and Batam, Indonesia. Unisem is listed on the Bursa Malaysia Securities Berhad.

### **About TSHT**

TSHT was incorporated in China on 25 December 2003, and is listed on Shenzhen Stock Exchange. TSHT has been growing continuously and rapidly for years through technological innovation, enhancement of internal management and other measures, which makes TSHT the second largest packaging and test enterprises in China. TSHT provides comprehensive assembly and test services to its customers with application across computers, communications, consumer electronics, Internet of Things, industrial automations and automotive electronics areas.